

CONFIRMED PLENARY AND INVITED SPEAKERS **Affiliation Authors Title** DARPA Todd Bauer Review of DARPA's T-MUSIC Program Hoi Lee University of Texas, Dallas High-efficiency high-conversion-ratio power delivery circuits for computing applications Steven Callender Intel D-Band meets FinFET: Fully-Integrated Transmitter and Receiver Architectures for 100+ Gb/s Links **Eric Bryerton** Virginia Diode Trends in mmW & THz Test Equipment 300-GHz-Band InP HBT Power Amplifier and InP-CMOS Teruo Jyo, NTT Munehiko Nagakani Hybrid Phased-Array Transmitter Alyosha C. Molnar Cornell University N-path mixers beyond CMOS Pascal Chevalier ST Microelectronics A 55-nm Flexible SiGe BiCMOS Technology for Wired, Wireless, and Satcom Applications Takuya Maeda University of Tokyo Characterization of ScAIN/GaN Toward Electronic **Device Application** III-V Semiconductors in Commercial Communication Jim Sowers Maxar Space Infrastructure Satellite Payloads Kenle Chen University of Central Florida Load Modulated Balanced Amplifiers for Next-G Wireless Communications Bernhard Grote NXP Advances in GaN HEMT and GaN PA techniques for base-stations Lan Wei University of Waterloo A Family of Physics-Based Models for Monolithic GaN Integration Larry Dunleavy Modelithics Inc., Practical Dimensions on Contemporary GaN HEMT University of South Florida Modeling Alexander Rylyakov Nokia Next Generation Optical Transceiver for Data Center Interconnect Christian Reimer Integrated Photonics in Thin-Film Lithium Niobate Hyperlight Tsunenobu Kimoto **Kyoto University** SiC Power Devices for Extreme Environment Operation Tumay Kanar Renesas Electronics Devices, technologies and challenges for SATCOM applications Zlatan Stanojevic Global TCAD Process to Parasitics Simulations

Randy Wolf	GlobalFoundries	State of the Art in PA Design for Wireless applications -
		Opportunities and challenges for compact modeling